

In the Claims:

Amend claims 1 and 2, as follows. [Format corresponding to 37 CFR §1.121(c)(i), ie. "without markings".]

1(Amended). A titanium target for sputtering comprising a titanium sputtering target in which a concentration of oxygen contained in the titanium target is less than 20ppm and an average grain diameter of said target is 20 μ m or less.

3 2(Amended). A titanium target for sputtering comprising a titanium sputtering target in which an impurity concentration of gas components including oxygen, nitrogen and hydrogen contained in the titanium target is 20ppm or less.

Add new claims 5-14, as follows:

5(New). A titanium sputtering target according to claim 1, wherein said target has a Vickers hardness (Vs) of 120 or less.

4 6(New). A titanium sputtering target according to claim 1, wherein said target has a total content of alkali metals and alkali earth metals including Na and K of 5ppm or less, a total content of heavy metals and light metals of 10ppm or less, and a total content of radioactive elements including U and Th of 1ppb or less.

7(New). A titanium sputtering target according to claim 5, wherein said target has a total content of alkali metals and alkali earth metals including Na and K of 5ppm or less, a

total content of heavy metals and light metals of 10ppm or less, and a total content of radioactive elements including U and Th of 1ppb or less.

8(New). A titanium sputtering target according to claim 2, wherein said target has a Vickers hardness (Vs) of 120 or less.

9(New). A titanium sputtering target according to claim 2, wherein said target has a total content of alkali metals and alkali earth metals including Na and K of 5ppm or less, a total content of heavy metals and light metals of 10ppm or less, and a total content of radioactive elements including U and Th of 1ppb or less.

10(New). A titanium sputtering target according to claim 8, wherein said target has a total content of alkali metals and alkali earth metals including Na and K of 5ppm or less, a total content of heavy metals and light metals of 10ppm or less, and a total content of radioactive elements including U and Th of 1ppb or less.

11(New). A titanium sputtering target according to claim 2, wherein said target has an average grain diameter of $20\mu\text{m}$ or less.

12(New). A titanium sputtering target according to claim 8, wherein said target has an average grain diameter of $20\mu\text{m}$ or less.

13(New). A titanium sputtering target according to claim 9, wherein said target has an average grain diameter of $20\mu\text{m}$ or less.

